



SOT364-1

plastic thin shrink small outline package; 56 leads; body width 6.1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP56
Package type industry code	TSSOP56
Package style descriptive code	TSSOP (thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

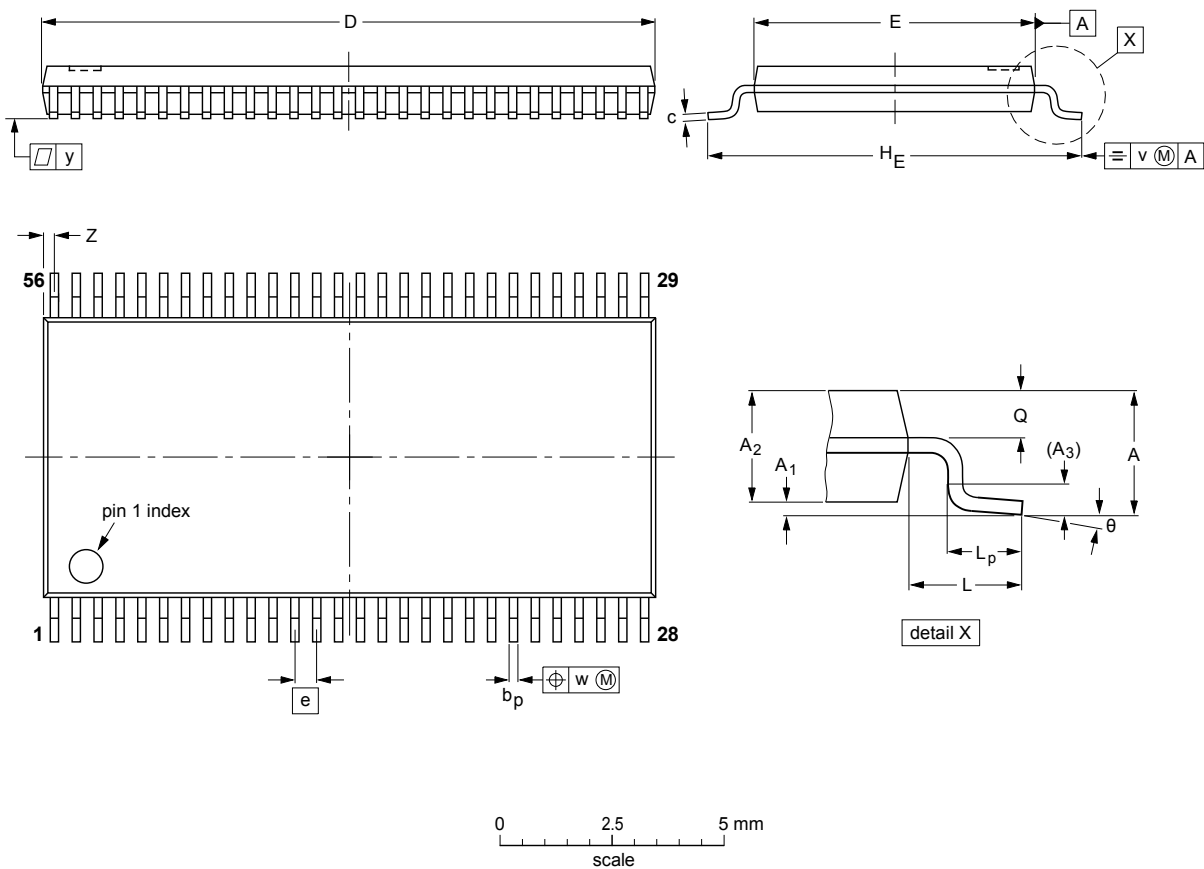
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		13.9	-	14	14.1	mm
E	package width		6	-	6.1	6.2	mm
A	seated height		[tbd]	-	1.2	1.2	mm
A ₂	package height		0.85	-	0.9	1.05	mm
n ₂	actual quantity of termination		-	-	56	-	



2. Package outline

TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1 mm

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DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT364-1		MO-153				99-12-27 03-02-19

Fig. 1. Package outline TSSOP56 (SOT364-1)

3. Soldering

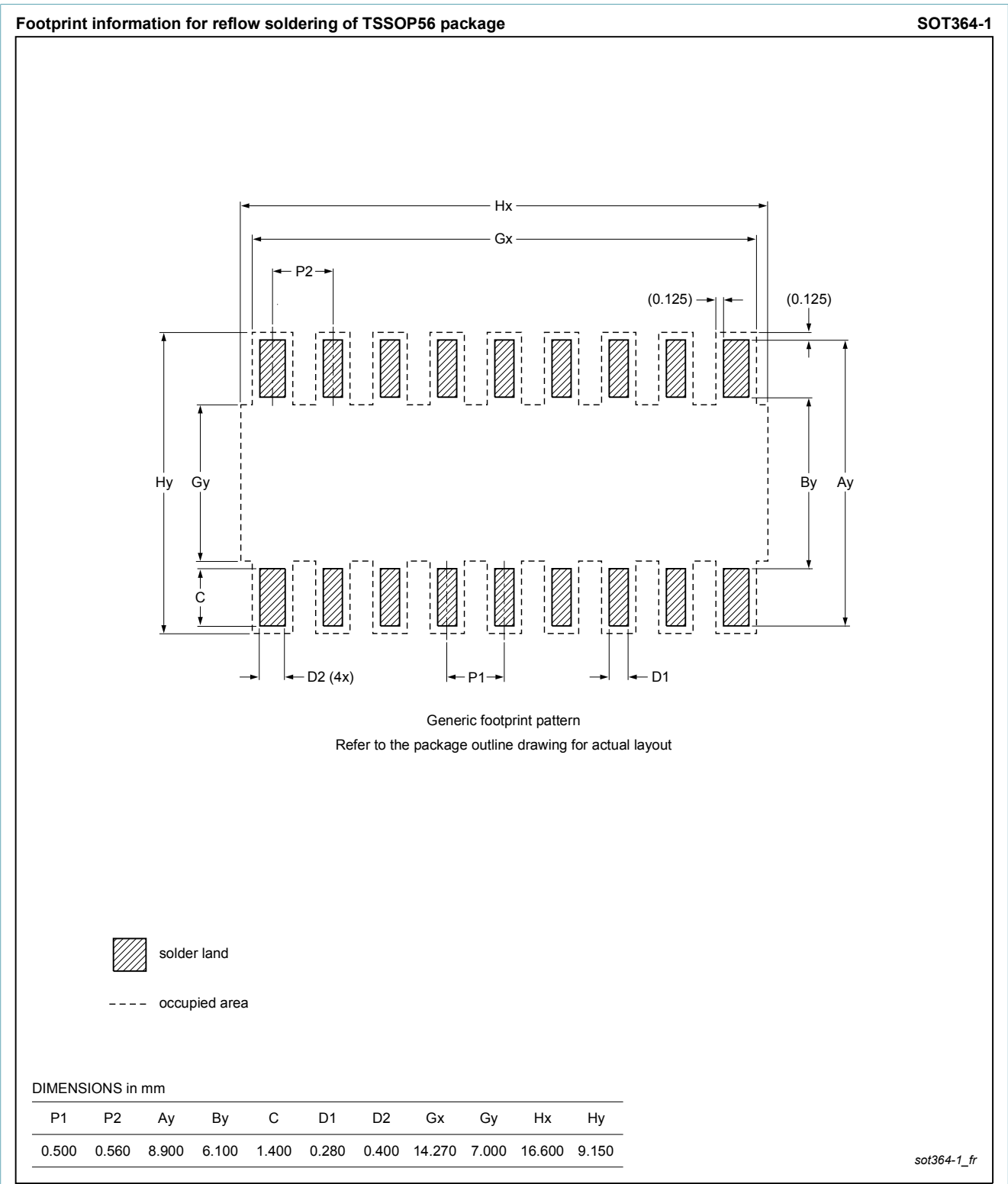


Fig. 2. Reflow soldering footprint for TSSOP56 (SOT364-1)

4. Legal information

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